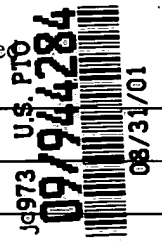


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| Subst. Form PTO-1449 APPLICANT'S INFORMATION DISCLOSURE STATEMENT | Atty. Docket No.: FIS920010127US1 (IFI-10-5579) | Serial No.: To be assigned |
| | Applicant: Casey, et al. | |
| | Filing Date: Herewith | Group: |



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| | AT | | | | | | |

Examiner:

Date Considered:

5/29/03

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered.
Include copy of this form with next communication to applicant.